TinyLogic ULP-A 2-Input Non-Inverting Multiplexer

NC7SV157

The NC7SV157 is a single 2-input non-inverting multiplexer in tiny footprint packages. The device is designed to operate for $V_{CC} = 0.9 \text{ V}$ to 3.6 V.

Features

- Designed for 0.9 V to 3.6 V V_{CC} Operation
- 1.9 ns t_{PD} at 3.3 V (Typ)
- Inputs/Outputs Over-Voltage Tolerant up to 3.6 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.3 V
- Available in SC-88A and MicroPakTM Packages
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

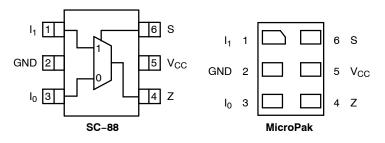


Figure 1. Pinout Diagrams (Top Views)

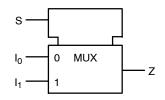


Figure 2. Logic Symbol

PIN ASSIGNMENT

Pin	Function
1	11
2	GND
3	10
4	Z
5	V _{CC}
6	S



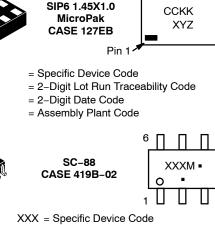
CC

KK

XY

Ζ

MARKING DIAGRAMS



= Date Code Μ

= Pb-Free Package

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 6 of this data sheet.

Inputs			Output	
S	I ₁	I ₀	$Z = (I_0) \cdot (\overline{S}) + (I_1) \cdot (S)$	
L	Х	L	L	
L	Х	Н	н	
Н	L	Х	L	
Н	Н	Х	Н	

H = HIGH Logic Level

L = LOW Logic Level

X = Don't Care

MAXIMUM RATINGS

Symbol	Characteristic	s	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +4.3	V
V _{IN}	DC Input Voltage		-0.5 to +4.3	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +4.3 -0.5 to +4.3	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	-50	mA	
IOUT	DC Output Source/Sink Current	±50	mA	
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground F	Pin	±50	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for 10 Sec	conds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SC-88A MicroPak	377 154	°C/W
PD	Power Dissipation in Still Air	SC-88A MicroPak	332 812	mW
MSL	Moisture Sensitivity		Level 1	-
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

should not be assumed, damage may occur and reliability may be affected.
Applicable to devices with outputs that may be tri-stated.
Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.
HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.
Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V _{IN}	DC Input Voltage		0	3.6	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 3.6 3.6	
T _A	Operating Temperature Range		-40	+85	°C
t _r , t _f	Input Transition Rise and Fall Time	$V_{CC}=3.3~V\pm0.3~V$	0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

				T	A = 25°	c	T _A = -40°0	C to +85°C			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Мах	Unit		
VIH	High-Level Input		0.9	_	0.5	-	-	-	V		
	Voltage		1.1 to 1.3	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-			
			1.4 to 1.6	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-			
			1.65 to 1.95	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-			
			2.3 to <2.7	1.6	-	-	1.6	-			
			2.7 to 3.6	2.0	-	-	2.0	-			
VIL	Low-Level Input		0.9	-	0.5	-	-	-	V		
	Voltage		1.1 to 1.3	-	-	$0.35 \times V_{CC}$	-	0.35 x V _{CC}			
			1.4 to 1.6	-	-	$0.35 \times V_{CC}$	_	0.35 x V _{CC}			
			1.65 to 1.95	-	-	$0.35 \times V_{CC}$	_	0.35 x V _{CC}			
					2.3 to <2.7	-	-	0.7	-	0.7	
			2.7 to 3.6	-	-	0.8	-	0.8			
V _{OH}	High-Level Output	$V_{IN} = V_{IH} \text{ or } V_{IL}$							V		
	Voltage	I _{OH} = -100 μA	0.9	_	V _{CC} – 0.1	-	-	-			
		1.1 to 1.3 1.4 to 1.6	1.1 to 1.3	$V_{CC}-0.1$	-	-	$V_{CC}-0.1$	-			
			$V_{CC} - 0.1$	-	-	V _{CC} - 0.1	-				
				1.65 to 1.95	$V_{CC} - 0.2$	-	-	$V_{CC} - 0.2$	-		
			2.3 to <2.7	$V_{CC}-0.2$	-	-	$V_{CC}-0.2$	-			
			2.7 to 3.6	$V_{CC} - 0.2$	-	-	$V_{CC} - 0.2$	-			
		$I_{OH} = -2 \text{ mA}$	1.1 o 1.3	$0.75 \times V_{CC}$	-	-	$0.75 \times V_{CC}$	-			
		I _{OH} = -4 mA	1.4 to 1.6	$0.75 \times V_{CC}$	-	-	$0.75 \times V_{CC}$	-			
		I _{OH} = -6 mA	1.65 to 1.95	1.25	-	-	1.25	-			
			2.3 to <2.7	2.0	-	-	2.0	-			
		I _{OH} = -12 mA	2.3 to <2.7	1.8	-	-	1.8	-			
			2.7 to 3.6	2.2	-	-	2.2	-			
		I _{OH} = -18 mA	2.3 to <2.7	1.7	-	-	1.7	-			
			2.7 to 3.6	2.4	-	-	2.4	-			
		I _{OH} = -24 mA	2.7 to 3.6	2.2	-	-	2.2	-			

DC ELECTRICAL CHARACTERISTICS (continued)

				٦	Γ _A = 25°	С	T _A = -40°	C to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
V _{OL}	Low-Level	$V_{IN} = V_{IH} \text{ or } V_{IL}$							V
	Output Voltage	I _{OL} = 100 μA	0.9	-	0.1	-	-	-	
			1.1 to 1.3	-	-	0.1	-	0.1	
			1.4 to 1.6	-	-	0.1	-	0.1	
			1.65 to 1.95	-	-	0.2	I	0.2	
			2.3 to < 2.7	-	-	0.2	-	0.2	
			2.7 to 3.6	-	-	0.2	-	0.2	
		I _{OL} = 2 mA	1.1 o 1.3	-	-	$0.25 \times V_{CC}$	-	$0.25 \times V_{CC}$	
		I _{OL} = 4 mA	1.4 to 1.6	-	-	$0.25 \times V_{CC}$	-	$0.25 \times V_{CC}$	
		I _{OL} = 6 mA	1.65 to 1.95	-	-	0.3	-	0.3	
		I _{OL} = 12 mA	2.3 to <2.7	-	-	0.4	-	0.4	
			2.7 to 3.6	-	-	0.4	-	0.4	
		I _{OL} = 18 mA	2.3 to <2.7	-	-	0.6	-	0.6	
			2.7 to 3.6	-	-	0.4	-	0.4	
		I _{OL} = 24 mA	2.7 to 3.6	-	-	0.55	-	0.55	
I _{IN}	Input Leakage Current	$V_{IN} = 0 V \text{ to } 3.6 V$	0.9 to 3.6	-	-	±0.1	-	±0.5	μA
I _{OFF}	Power Off Leakage Current	$V_{IN} = 0 V \text{ to } 3.6 V \text{ or}$ $V_{OUT} = 0 V \text{ to } 3.6 V$	0	_	-	0.5	-	0.5	μΑ
Icc	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	0.9 to 3.6	_	-	0.9	-	0.9	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

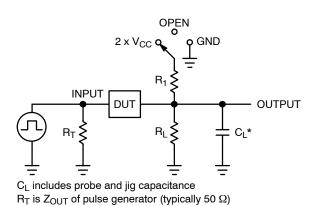
				1	Γ _A = 25°C)	T _A = -40°C	C to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Мах	Unit
t _{PLH} ,	Propagation Delay,	R_L = 1 M Ω , C_L = 15 pF	0.9	-	19.1	-	-	-	ns
t _{PHL}	(S or I ₀ or I ₁) to Z (Figures 3 and 4)	$R_L = 2 \text{ k}\Omega, C_L = 15 \text{ pF}$	1.1 to 1.3	-	6.3	15.5	-	18.8	
			1.4 to 1.6	-	3.8	8.5	-	9.5	
		R_L = 500 Ω , C_L = 30 pF	1.65 to 1.95	-	3.1	6.7	-	7.5	
			2.3 to 2.7	-	2.2	4.1	-	4.4	
			2.7 to 3.6	-	1.9	3.4	-	3.6	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Parameter Test Condition		
C _{IN}	Input Capacitance	V _{CC} = 0 V	2.0	pF
C _{OUT}	Output Capacitance	V _{CC} = 0 V	4.5	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	f = 10 MHz, V_{CC} = 0.9 to 3.6 V, V _{IN} = 0 V or V_{CC}	10.0	pF

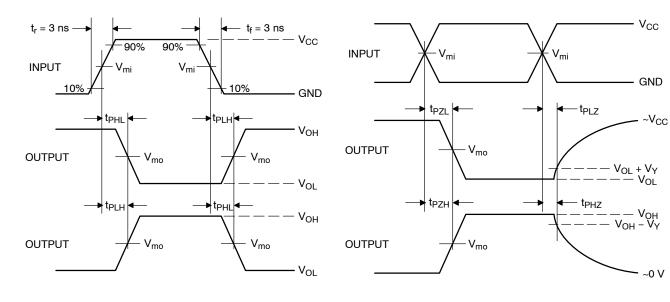
5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption: $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



f = 1 MHz

Test	Switch Position
t _{PLH} / t _{PHL}	Open
t _{PLZ} / t _{PZL}	2 x V _{CC}
t _{PHZ} / t _{PZH}	GND

Figure 3. Test Circuit



V _{CC} , V	V _{mi} , V	V _{mo} , V	V _Y , V
0.9	V _{CC} / 2	V _{CC} / 2	0.1
1.1 to 1.3	V _{CC} / 2	V _{CC} / 2	0.1
1.4 to 1.6	V _{CC} / 2	V _{CC} / 2	0.1
1.65 to 1.95	V _{CC} / 2	V _{CC} / 2	0.15
2.3 to 2.7	V _{CC} / 2	V _{CC} / 2	0.15
3.0 to 3.6	1.5	1.5	0.3

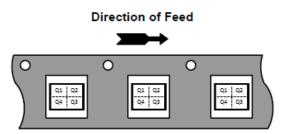
Figure 4. Switching Waveforms

ORDERING INFORMATION

Device	Package	Marking	Pin 1 Orientation (See below)	Shipping [†]
NC7SV157P6X	SC-88A	VF7	Q4	3000 / Tape & Reel
NC7SV157L6X	MicroPak	H9	Q4	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

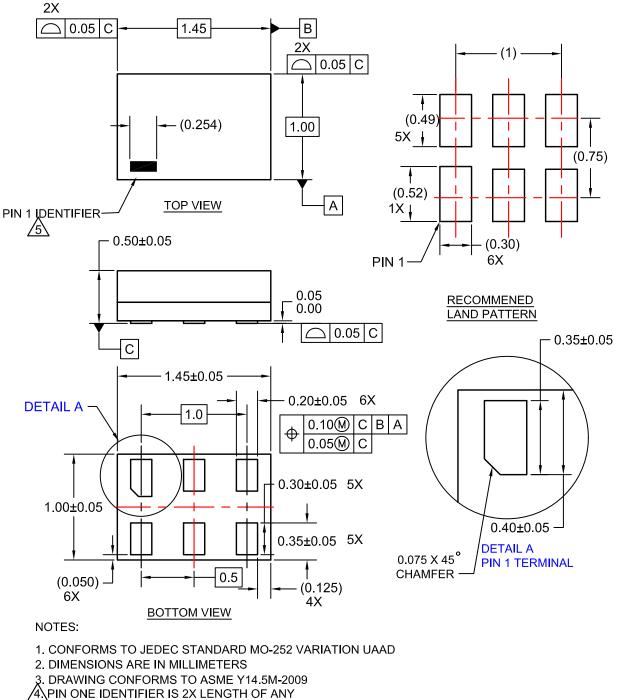
Pin 1 Orientation in Tape and Reel



MicroPak is trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

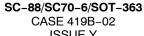
PACKAGE DIMENSIONS

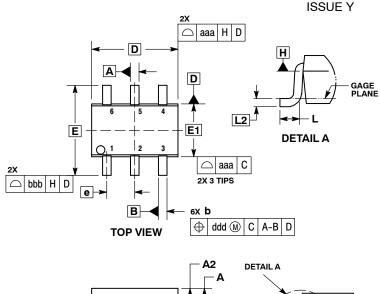
SIP6 1.45X1.0 CASE 127EB ISSUE O



OTHER LINE IN THE MARK CODE LAYOUT.

PACKAGE DIMENSIONS





A1

SIDE VIEW

NOTES:

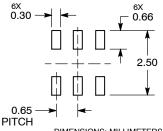
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. 2
- 3
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS, MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF 4
- THE PLASTIC BODY AND DATUM H. DATUMS A AND B ARE DETERMINED AT DATUM H. 5
- DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP. 6
- DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDI TION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC			0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			0.006 BSC		
aaa	0.15			0.006		
bbb	0.30			0.012		
ccc	0.10			0.004		
ddd	0.10			0.004		

END VIEW

RECOMMENDED SOLDERING FOOTPRINT*

С



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

6Х 🔾 ССС С

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North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910 For additional information, please contact your local Sales Representative